

SSM 4A / SSM 9

Repair of through hole technology



SSM 4A / SSM9

The SSM machines are used for selective soldering and de-soldering of multi-lead, through-hole technology components. The programmable parameters allow precise and repeatable results can be achieved, independent of the operator.

MAIN FEATURES

- Flexible solutions for **standard or irregularly shaped components**.
- **Reproducible soldering results due to defined process parameters** such as solder temperature, process time, wave height, ramp up and ramp down or regarding the SSM 9, up to 10 programmable parameters.
- **Easy height adjustment of the PCB above the flow channel.**
- Stable construction: **Easy to use and stable table top machine.**
- Even **irregularly shaped boards up to a size of 840 mm x 600 mm can be fixed** on the quick locking board holder.
- **Blow out** option to clean the solder joints after removing a connector.
- **Application specific tools for any type of component**, even on densely populated boards, including multi-solder solutions, for wetting defined positions.
- **Optional preheater module PH 4**, specially for lead-free applications.
- **Lead-free retrofit:** Already installed machines can be retrofitted for lead-free applications.



MARKET REQUIREMENTS

Enhanced effectiveness

- Fast positioning with the air nozzle.
- Soldering and de-soldering at the same time / position.
- Reliable blow-out of solder holes from above, immediately after removal of the device.

Improved quality

- Precise adjustment of soldering parameters.
- Reproducible results.
- Non-mechanical stress protects device and circuit board against damage.
- Adjacent devices are protected during soldering process.
- Heat is isolated to a single component.

SELECTIVE SOLDERING, THROUGH-HOLE TECHNOLOGY

Up to ten programmable parameters such as solder temperature, cycle time, wave height, ramp up and ramp down to ensure precise and repeatable soldering results.

APPLICATION RANGE

Repairs

Damaged components can be replaced.

Prototyping

The SSM 4 and SSM 9 can be used to efficiently assemble and solder prototypes.

Retrofits

- Components which are missing at production time.
- On the solder side, components need to be placed.
- An SMD board needs to be extended with single wired components.

Soldering

The SSM 4 and SSM 9 soldering and de-soldering machines are often the simplest and most economical way to assemble printed circuit boards with a small number of components.

Saves time

The system's ergonomic design speeds up and simplifies your work, producing results that meet the highest quality standards.

No Restrictions

Even the most difficult soldering and de-soldering jobs can be carried out reliably with the SSM 4 and SSM 9:

- Multi-layer board operations.
- Processes components with complex geometries such as DIP switches and long connectors.
- Operates on dense mixed technology boards.
- Component-side soldering, even between adjacent high components.
- Soldering and de-soldering of pin grid arrays and sockets.
- Soldering on flex boards.



OPTIONAL PREHEATER MODULE PH 4

To improve the performance for lead-free applications

The PH 4 preheater module can be used as a stand-alone device or together with the SSM 4A or the SSM 9. By preheating the PCB before the selective soldering process is carried out the risk of copper delamination is reduced. The preheater PH 4 uses IR technology to preheat the printed circuit board on an area of 300 x 300 mm with a performance of 3500 watt.

SSM 4A

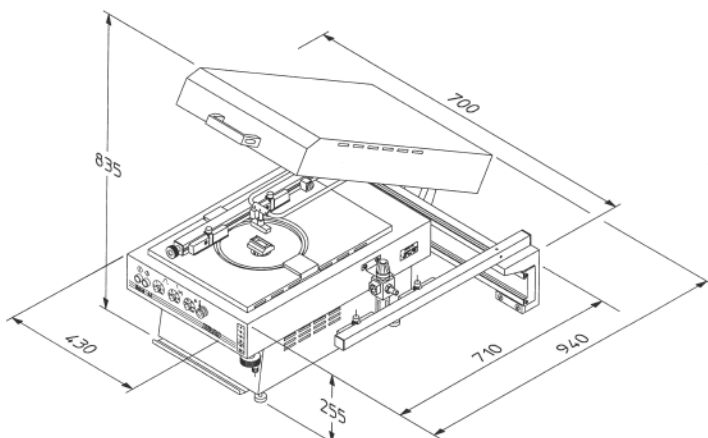
The SSM 4A is used for selective soldering and de-soldering of multi-polar trough hole components (THT). Due to defined process parameters repeatable results can be achieved.



TECHNICAL DATA

Product designation	SSM 4A
Max. board size	600 mm x 600 mm
Pumping system	Solder pump
Heat up time	Approx. 30 min
Cycle duration	0 - 60 s
Air pressure	1 - 8 bar
Solder temperature	200 °C - 300 °C
Max. power consumption	2500 W
Power requirements	220 - 230 Volt, 50 Hz
Dimensions (W x D x H)	440 mm x 800 mm x 360 mm
Solder content	Approx. 16 kg
Weight (without solder)	47 kg

DIMENSIONS



SSM 9

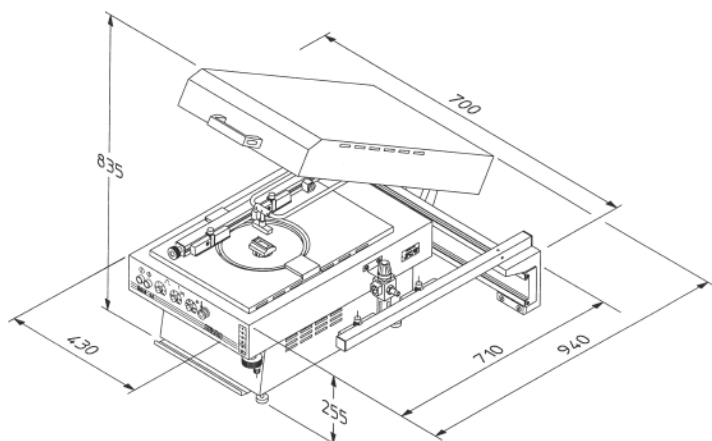
The SSM 9 is used for selective soldering and de-soldering of multi-polar trough hole components. Due to the programmable parameters precise and repeatable results can be achieved, user-independent.



TECHNICAL DATA

Product designation	SSM 9
Max. board size	840 mm x 600 mm
Pumping system	Solder pump
Heat up time	Approx. 30 min
Cycle duration	0 - 60 s
Air pressure	1 - 8 bar
Solder temperature	235 °C - 400 °C
Max. power consumption	2500 W
Power requirements	220 - 230 Volt, 50 Hz
Dimensions (W x D x H)	440 mm x 800 mm x 360 mm
Solder content	Approx. 16 kg
Weight (without solder)	75 kg

DIMENSIONS



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